ABSTRACT OF THE DISCLOSURE

When honing an abrasive pad for polishing a wafer by rotating while closely contacting the wafer by bringing a conditioner into contact with the abrasive pad, forces applied from the abrasive pad to the conditioner are detected by a plurality of pressure detectors through a conditioner driving unit for holding the conditioner. The pressure detectors are respectively able to detect forces in two directions such as rotational direction and radial direction. A memory stores correlations between detection values and wafer polishing quantities under various conditioning terms. Therefore, it is determined whether the detection values are kept within acceptable limits stored in the memory. When the values are out of the acceptable limits, a controller controls the values so that they fall within the acceptable limits by properly changing conditioning terms. Thus, the controller accurately detects and controls the surface state of the abrasive pad so that the surface state falls within a proper range and a wafer can be stably polished at a predetermined polishing quantity.